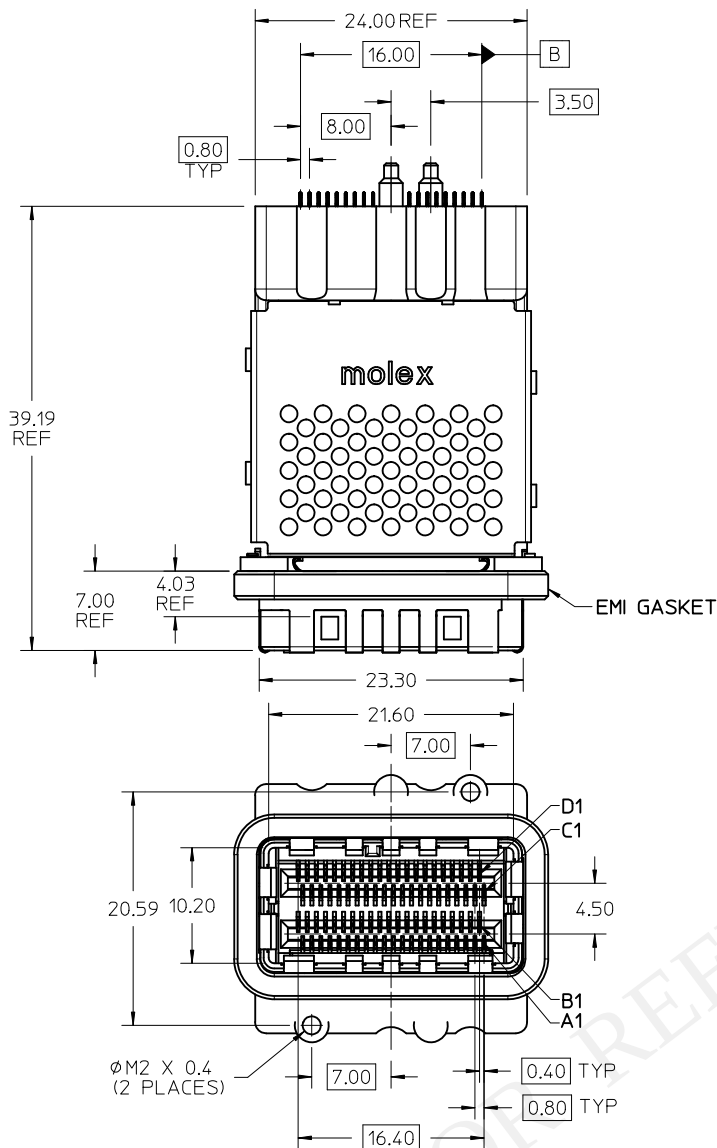
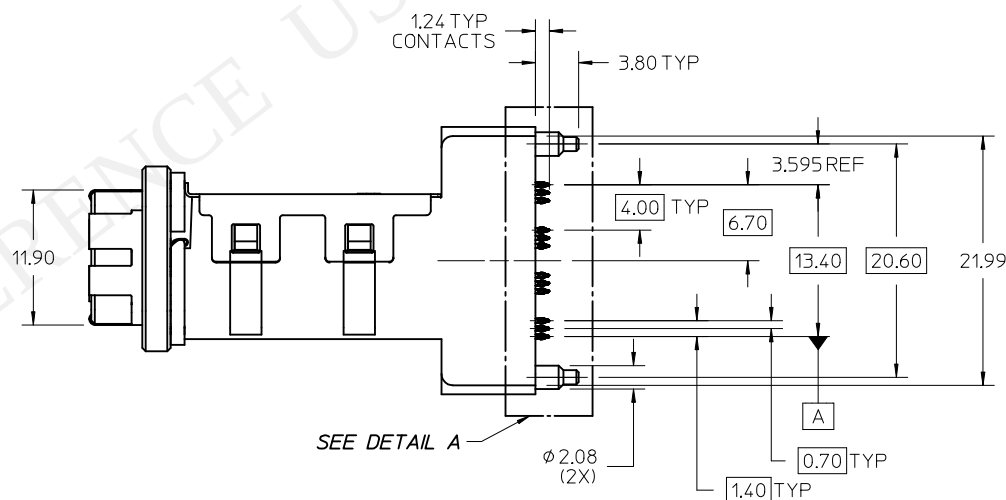
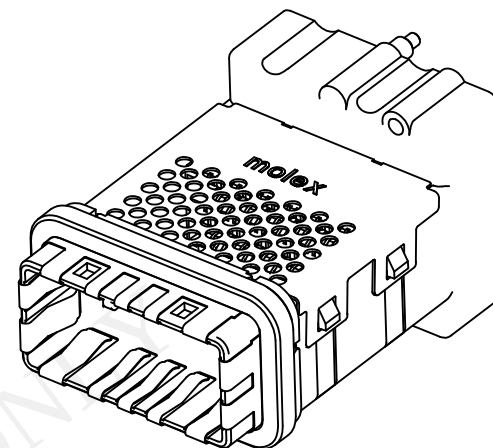
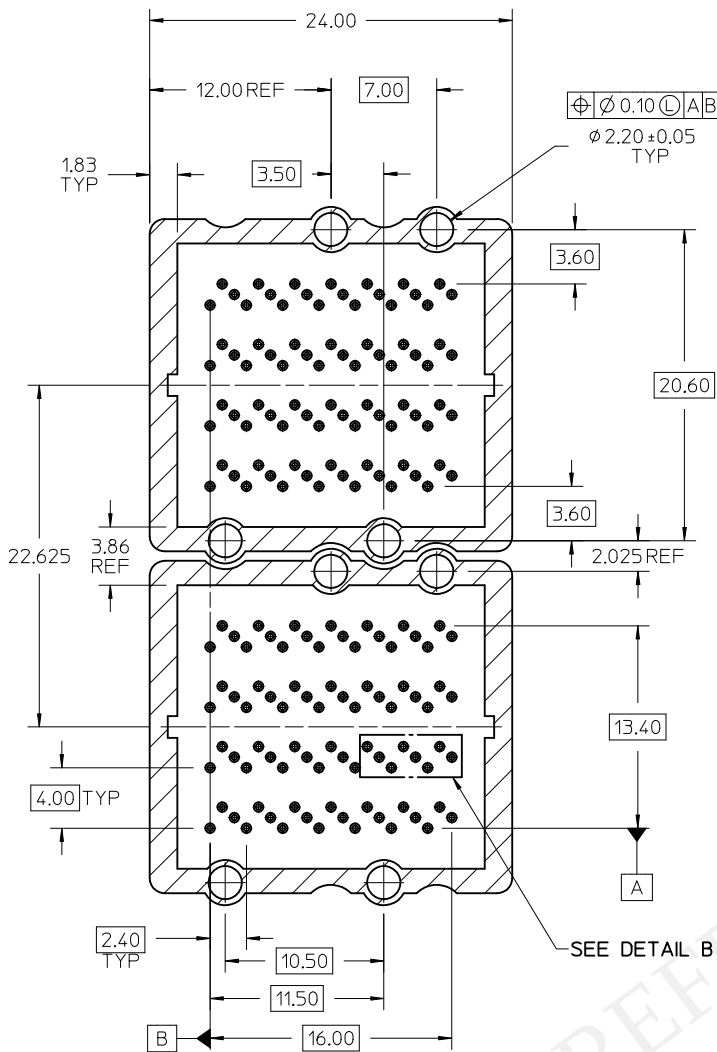


DETAIL A
SCALE 4:1

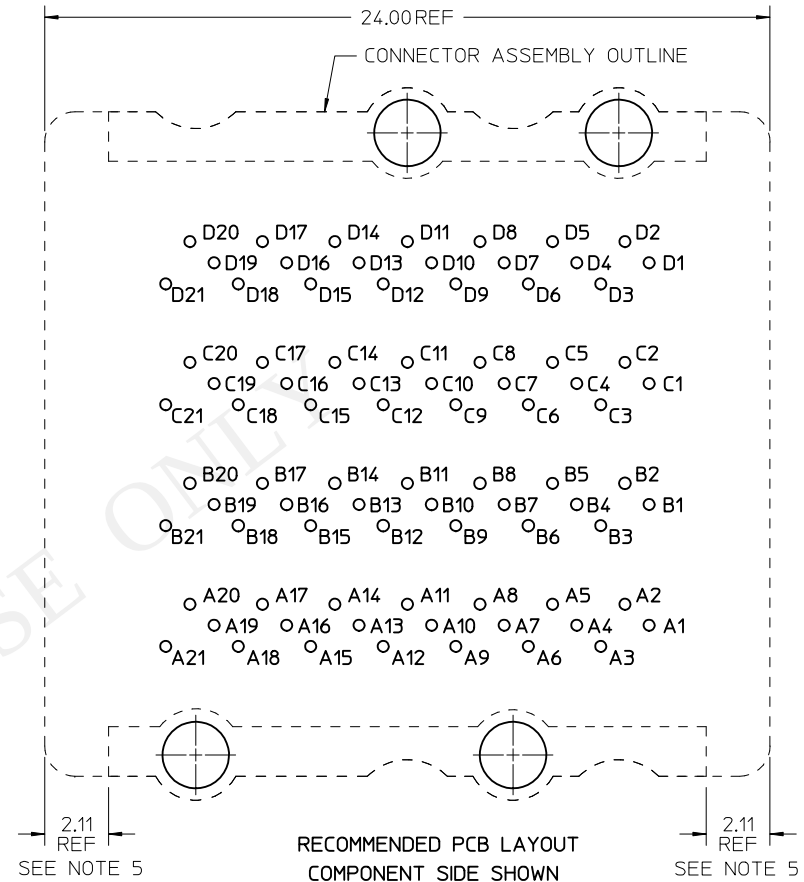


- NOTES:
- MATERIALS:
CONNECTOR HOUSING: HIGH TEMPERATURE THERMOPLASTIC
GLASS-FILLED, UL 94V-0
EMI HOUSING: NICKEL PLATED DIE CAST ALLOY
COVER: STAINLESS STEEL ALLOY
EMI GASKET: CONDUCTIVE POLYMER
TERMINALS: COPPER ALLOY
 - PLATING:
769970022 - CONTACT AREA: 0.764mm MIN. GOLD OVER 2.544mm MIN. NICKEL
TIN TAIL AREA: 0.764mm - 1.524mm TIN OVER 2.544mm MIN NICKEL
 - THIS CONNECTOR IS DESIGNED TO MATE WITH MOLEX IPASS CABLES.
 - PACKAGING SPECIFICATION: TRAY PACK PER PK-76997-001.
 - MOUNTING HARDWARE REQUIRED: M2x0.4 CAP SCREWS (4), SEE SHEET 3
 - PRODUCT SPECIFICATION: PS-76997-001.
 - APPLICATION SPECIFICATION: AS-76997-001.

RELEASE TO 'A' EC NO: UCP2013-3343 DRAWING PRATT 2012/10/17 CHKD: MBANAKIS 2013/02/07 APPR: MBANAKIS 2013/02/13			DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION
						mm	INCH	DRAWN BY GPRATT	DATE 2013/02/07	TITLE VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O			
A	REV				4 PLACES	± ---	± ---	CHECKED BY MBANAKIS	DATE 2013/02/07	molex SD-76997-242			
					3 PLACES	± ---	± ---	APPROVED BY MBANAKIS	DATE 2013/02/13				
					2 PLACES	± 0.25	± ---	MATERIAL NO.					
					1 PLACE	± ---	± ---	SEE CHART					
					0 PLACE	± ---	± ---	DOCUMENT NO.					
				ANGULAR ±1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
										SHEET NO. 1 OF 3			

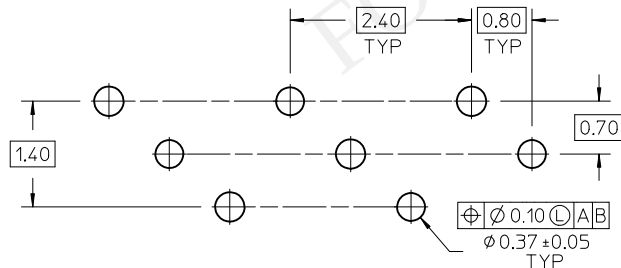


RECOMMENDED PCB LAYOUT
COMPONENT SIDE SHOWN
MULTIPLE APPLICATION SHOWN
ON MINIMUM PITCH
PCB THICKNESS: 1.57mm MIN.



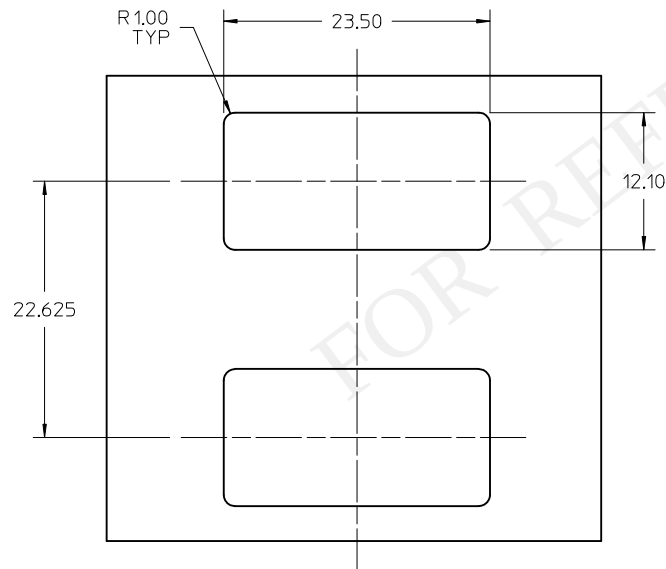
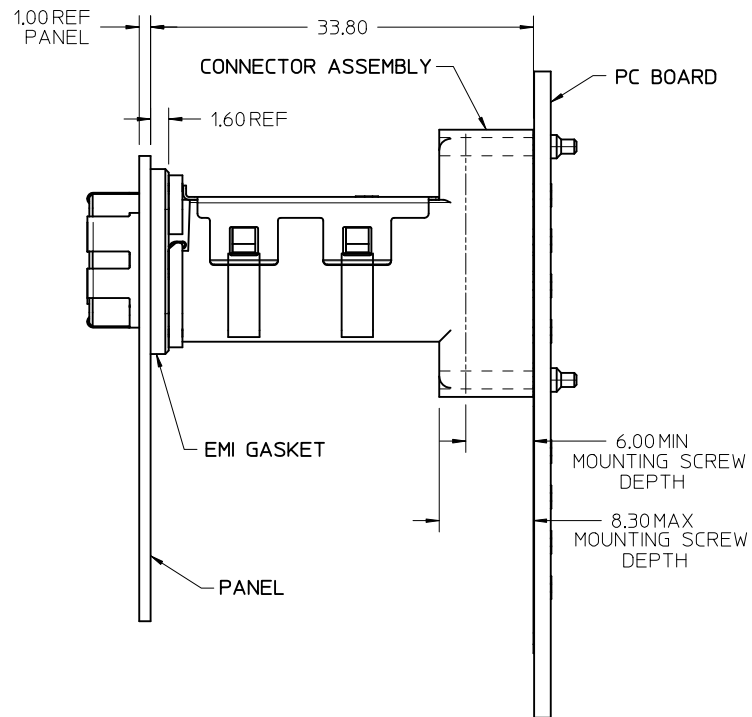
NOTES:

- CROSS-HATCHED AREA TO BE CONDUCTIVE ON THE PCB.
- CROSS-HATCHED AREA MUST BE INCORPORATED IN THE FLAT ROCK PRESS-FIT TOOLING.
- REFER TO THE PLATING DETAIL OF THE COMPLIANT PIN HOLES IN THE APPLICATION SPEC AS-76997-002 FOR THE DRILL SIZE AND ANNULAR RING FOR THE 0.37 ϕ FINISHED HOLE.
- DIE CAST RELEIVED 1.5MM IN THIS AREA.

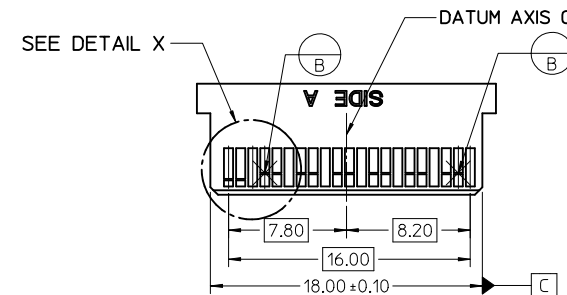
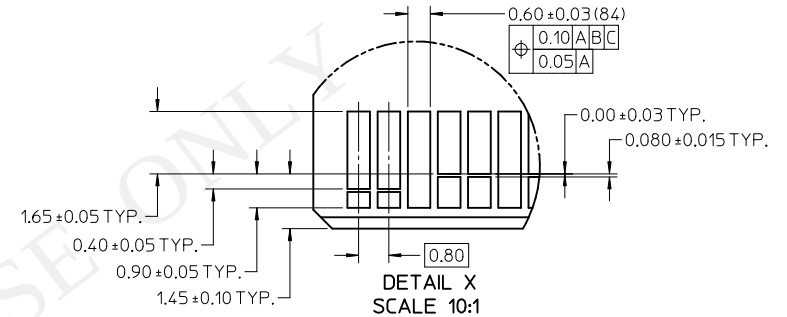
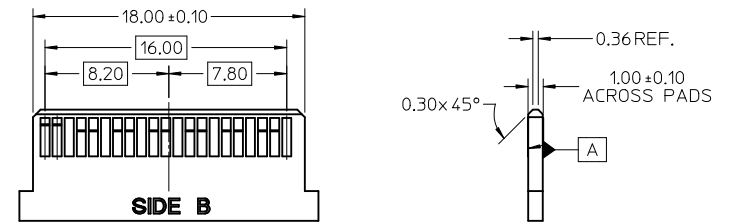


DETAIL B
(TYPICAL ROW LAYOUT)

SEE SHEET 1	EC NO: UCP2013-3343 2012/10/17 DRWG:GPRATT CHKD:MBANAKIS 2013/02/07 APP:MBANAKIS 2013/02/13			DESCRIPTION REV A	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O molex DOCUMENT NO. SD-76997-242 SHEET NO. 2 OF 3			
	mm		INCH			DRAWN BY GPRATT		DATE 2013/02/07		TITLE							
	4 PLACES ±---		±---			CHECKED BY MBANAKIS		DATE 2013/02/07									
	3 PLACES ±---		±---			APPROVED BY		DATE									
	2 PLACES ±0.25		±---			MBANAKIS		2013/02/13									
	1 PLACE ±---		±---														
	0 PLACE ±---		±---														
	ANGULAR ±1/2°					MATERIAL NO.						SHEET NO.					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					SEE SHEET 1											
						SIZE				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



I/O PANEL CUT-OUT



- NOTES:
- 0.03 MINIMUM KEEP OUT FOR SOLDER MASK AROUND ALL PADS
 - DATUM B TARGETS ARE DEFINED BY THE RESPECTIVE PAD CENTER LINES AND THE LEADING EDGE OF THE TARGET PADS

RECOMMENDED PADDLE CARD LAYOUT

SEE SHEET 1 EC NO: UCP2013-3343 DRAWN BY: GPRATT CHKD: MBANAKIS APPR: MBANAKIS	REV A	DESCRIPTION 2012/10/17 2013/02/07 2013/02/13	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O molex	
				4 PLACES	± ---	± ---	DRAWN BY GPRATT	DATE 2013/02/07	TITLE		
				3 PLACES	± ---	± ---	CHECKED BY	DATE			
				2 PLACES	± 0.25	± ---	MBANAKIS	2013/02/07			
				1 PLACE	± ---	± ---	APPROVED BY	DATE			
				0 PLACE	± ---	± ---	MBANAKIS	2013/02/13			
				ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.			SHEET NO.
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-76997-242		3 OF 3					
		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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